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AVIDISPLAY

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# SPECIFICATION FOR TFT MODULE

**MODULE NO. : T1011126-01A-GDN**

**CUSTOMER NO. :**

**Rev No. : 0**

AVD	PREPARED BY	CHECKED BY	APPROVED BY
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DATE	2022.08.18	2022.08.18	2022.08.18

CUSTOMER APPROVAL	SIGNATURE	DATE

Notes :

- 1、Please contact AVD before assigning your product based on this module specification.
- 2、To improve the quality of product, and this product specification is subject to change without any notice.

P. 1

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## 1. GENERAL INFORMATION

No.	Item	Contents	Unit
1	LCD size	10.1 inch (Diagonal)	/
2	Display mode	IPS/Normally white/TRANSMISSIVE	/
3	Viewing direction(eye)	FREE	/
4	Gray scale inversion direction	-	/
5	Resolution(H*V)	800 *1280 Pixels	/
6	Module size (L*W*H)	163.10*244.30*4.61	mm
7	Active area (L*W)	135.36*216.58	mm
8	Pixel pitch (L*W)	0.1692*0.1692	mm
9	Interface type	MIPI interface(TFT)/I2C(CTP)	/
10	Color Depth	16.7M	/
11	Module power consumption	TBD(Appr)	W
12	Back light type	EDGE&WHITE LED	/
13	Driver IC	SC7705 OR COMPATIBLE(TFT) GT9271(CTP)	/
14	Weight	TBD(Appr)	G

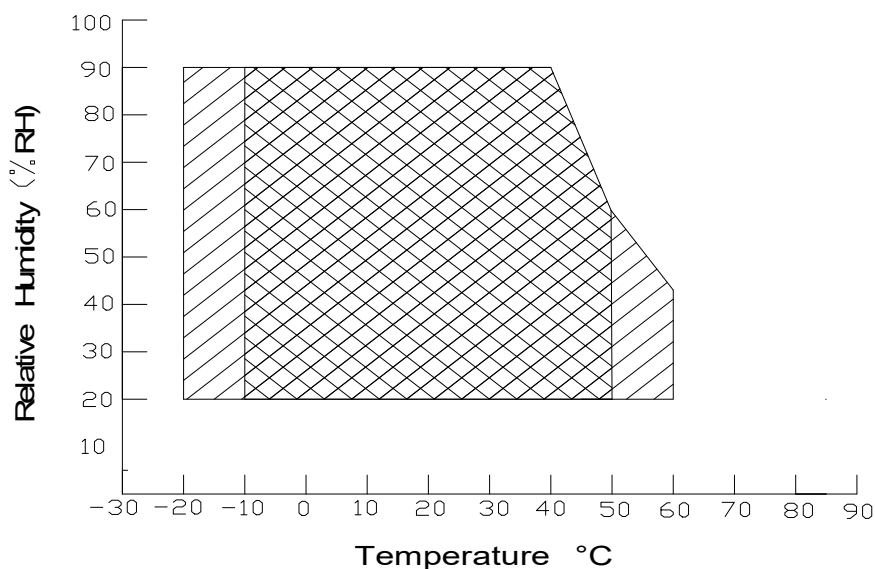
## 2. ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Min.	Max.	Unit	Note
Power supply input voltage for TFT	VDD	-0.3	5.5	V	
Power supply input voltage for CTP	VCC	-0.3	3.47	V	
Backlight current (normal temp.)	ILED	-	125	mA	
Operation temperature	Top	-10	+50	°C	Note1
Storage temperature	Tst	-20	+60	°C	Note1
Humidity	RH	20%	90%	/	Note1

Note1 :

1).The relative humidity and temperature range are as below sketch,90%RH Max.

2).The maximum wet bulb temperature  $\leq 40^{\circ}\text{C}$  and without dewing.



Operating Range



Storage Range





### 3. ELECTRICAL CHARACTERISTICS

#### TFT DC CHARACTERISTICS(at Ta=25℃)

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Power supply input voltage	VCC	3.1	3.3	3.3	V	
I/O logic voltage	VDDIO	-	-	-	V	
Input voltage 'H' level	VIH	0.7VCC	-	VCC	V	
Input voltage 'L' level	VIL	VSS	-	0.3VCC	V	
Power supply current	IVDD	-	TBD	-	mA	
TFT gate on voltage	VGH	-	-	-	V	
TFT gate off voltage	VGL	-	-	-	V	
Analog power supply voltage	AVDD	-	-	-	V	
TFT common electrode voltage	VCOM	-	-	-	V	Note1

Note1 : The value is just the reference value. The customer can optimize the setting value by the different D-IC  
VCOM must be adjusted to optimize display quality, as Crosstalk and Contrast Ratio etc..

#### CTP DC CHARACTERISTICS(at Ta=25℃)

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Power supply input voltage	VCC3.3	3.1	3.3	3.47	V	Note1
Input Power ripple	Vpp	-	-	50	mV	
I/O Signal Voltage	IOVCC	-	1.8	-	V	Note1
Input voltage 'H' level	VIH	1.35	1.8	2.1	V	
Input voltage 'L' level	VIL	-0.3	0	0.45	V	
Operating Current (Normal Mode)	IVCC	-	13	-	mA	
Operating Current (Sleep mode)	IVCC	-	-	-	mA	

Note1 : If you need more information of CTP, please refer to our Spec of CTP.

### 4. BACKLIGHT CHARACTERISTICS

(at Ta=25℃, RH=60%)

Item	Symbol	Min.	Typ.	Max.	Unit	Note
LED forward voltage	VF	19.6	21.0	23.1	V	
LED forward current	IF	-	100	-	mA	IF=25*4mA
LED power consumption	PLED	-	2.1	-	W	Note1
Number of LED	-		28		PCS	
Connection mode	-	7 in series 4 in parallel			/	
LED life-time	-	20000	-	-	Hrs	Note2

Note1 : Calculator value for reference : IF\*VF = PLED

Note2 : The LED life-time define as the estimated time to 50% degradation of initial brightness at Ta=25℃ and IF =100mA. The LED lifetime could be decreased if operating IF is larger than 100mA.

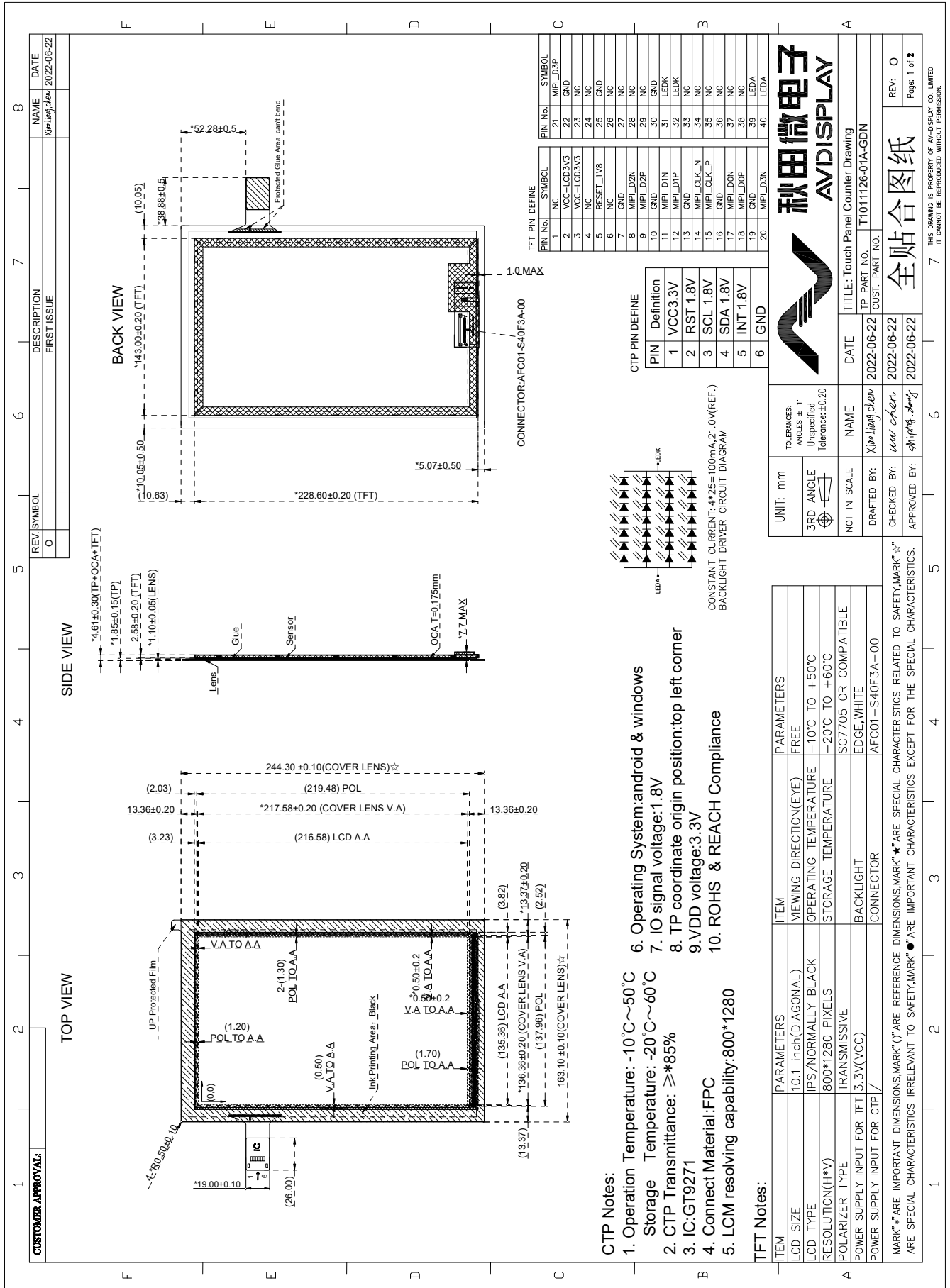
### 5. TOUCH PANEL CHARACTERISTICS

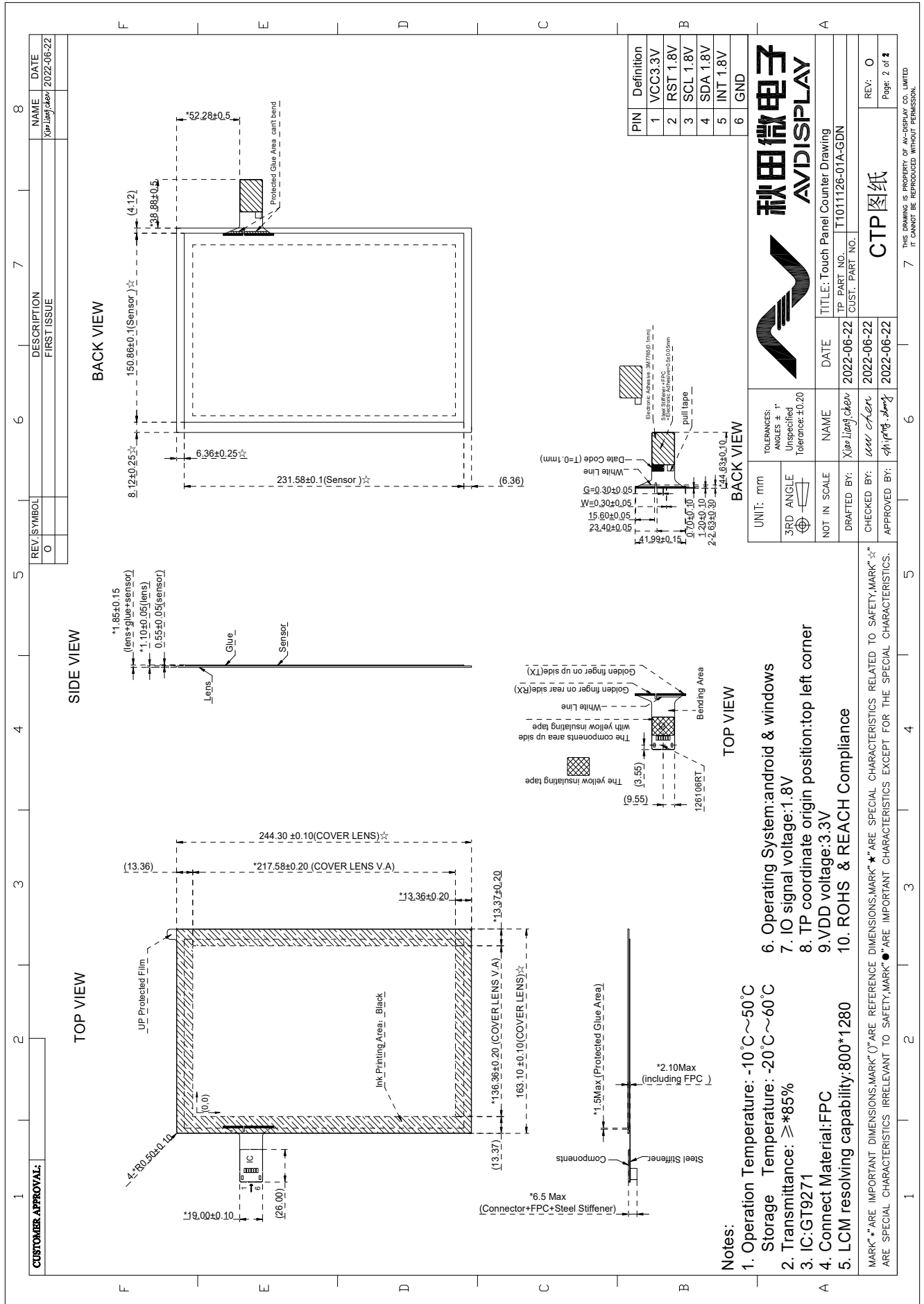
(at Ta=25℃)

Item	Description	Remark
Product Structure	G+G	
Surface Hardness	6H	Pencil, Loading 1000g, 45 deg
Ball-falling Test	70cm	Steel ball weight 64g
Touch Count Max	10 point	
I2C Slave Address*	0x5D	
Origin of Coordinate*	top left corner	
FW version	1050	



## 6. EXTERNAL DIMENSIONS





## 7. ELECTRO - OPTICAL CHARACTERISTICS

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Remark	Note
Response time	Tr+ Tf	-	-	30	-	ms	FIG.1	Note 1
Contrast ratio	Cr		640	800	-	-	FIG.2	Note 2
Surface luminance	Lv	$\theta=0^\circ$	200	250	-	cd/m <sup>2</sup>	FIG.2	Note 3
Luminance uniformity	Yu	$\theta=0^\circ$	75	80	-	%	FIG.2	Note 4
NTSC	-	$\theta=0^\circ$	52	56	-	%	FIG.2	Note 5
Viewing angle	$\theta$	$\phi=90^\circ$	70	80	-	deg	FIG.3	Note 6
		$\phi=270^\circ$	70	80	-	deg	FIG.3	
		$\phi=0^\circ$	70	80	-	deg	FIG.3	
		$\phi=180^\circ$	70	80	-	deg	FIG.3	
CIE (x,y) chromaticity	Red x	$\theta=0^\circ$ $\phi=0^\circ$ $T_a=25^\circ\text{C}$	Typ -0.04	TBD	Typ +0.04	-	FIG.2 CIE1931	Note 5
	Red y			TBD		-		
	Green x			TBD		-		
	Green y			TBD		-		
	Blue x			TBD		-		
	Blue y			TBD		-		
	White x			TBD		-		
	White y			TBD		-		

### Note1. Definition of response time

The response time is defined as the LCD optical switching time interval between “White” state and “Black” state. Rise time ( $T_{ON}$ ) is the time between photo detector output intensity changed from 90% to 10%. And fall time ( $T_{OFF}$ ) is the time between photo detector output intensity changed from 10% to 90%. For additional information see FIG1.

### Note2. Definition of contrast ratio

Contrast ratio(Cr) is defined mathematically by the following formula.  
For more information see FIG.2.

$$\text{Contrast ratio} = \frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$$

Measured at the center area of the LCD

### Note3. Definition of surface luminance

Surface luminance is the luminance with all pixels displaying white.  
For more information see FIG.2.

$L_v$  = Average Surface Luminance with all white pixels( $P_1, P_2, P_3, \dots, P_n$ )

### Note4. Definition of luminance uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance. For more information see FIG.2.

$$Y_u = \frac{\text{Minimum surface luminance with all white pixels } (P_1, P_2, P_3, \dots, P_n)}{\text{Maximum surface luminance with all white pixels } (P_1, P_2, P_3, \dots, P_n)}$$

### Note5. Definition of color chromaticity (CIE1931)

CIE (x,y) chromaticity, The x,y value is determined by screen active area center position P5. For more information see FIG.2.

### Note6. Definition of viewing angle

Viewing angle is the angle at which the contrast ratio is greater than 10. angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface.  
For more information see FIG.3.

For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope or DMS series Instruments or compatible. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on TOPCON's BM-7 photo detector or compatible.



FIG.1. The definition of response Time

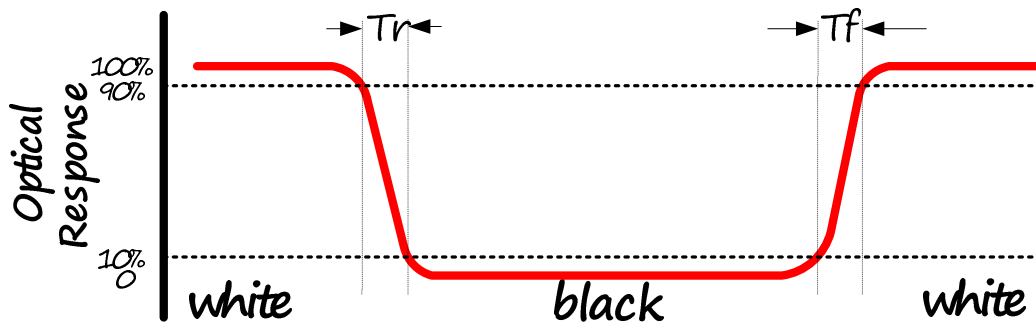


FIG.2. Measuring method for contrast ratio, surface luminance, luminance uniformity, CIE (x,y) chromaticity

Note : The TFT module should be stabilized at a given temperature for 10 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 10 minutes in a windless room.

H,V : Active area

Light spot size  $\varnothing=5\text{mm}$  (CS-2000/BM-7) 50cm distance or compatible distance from the LCM surface to detector lens.

Test spot position : see Figure a.

measurement instrument : TOPCON's luminance meter CS-2000/BM-7 or compatible ,see Figure b.

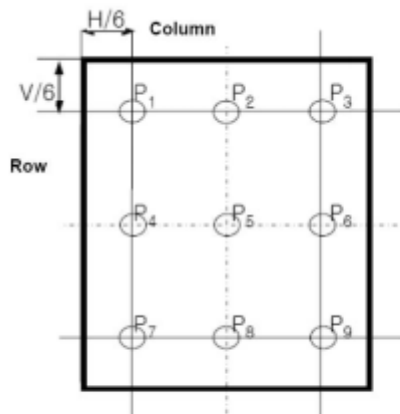


Figure a

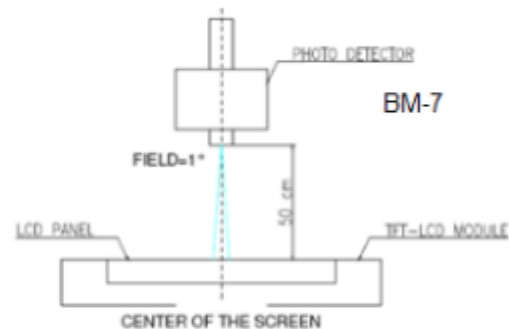
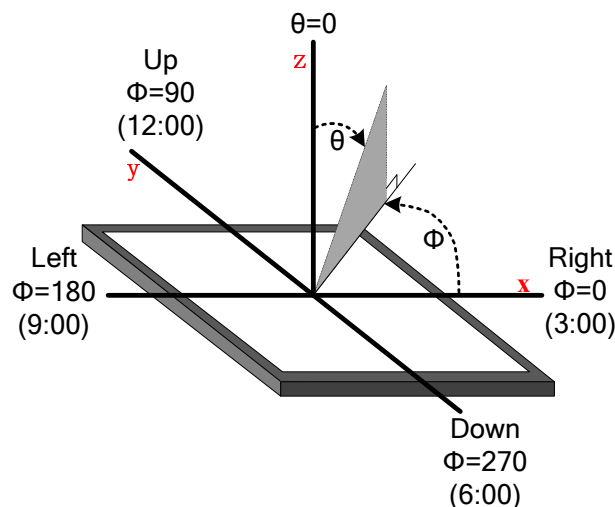


Figure b

FIG.3. The definition of viewing angle





## 8. INTERFACE DESCRIPTION

### TFT Module Interface description

Interface No.	Name	I/O or connect to	Description
1	NC	/	/
2-3	VCC-LCD3V3	P	Power for LCD
4	NC	/	/
5	RESET_1V8	I	The external reset input
6	NC	/	/
7	GND	P	Power ground
8	MIPI_D2N	I	Negative DSI Data2 differential signal input pins
9	MIPI_D2P	I	Positive DSI Data2 differential signal input pins
10	GND	P	Power ground
11	MIPI_D1N	I	Negative DSI Data1 differential signal input pins
12	MIPI_D1P	I	Positive DSI Data1 differential signal input pins
13	GND	P	Power ground
14	MIPI_CLK_N	I	Positive DSI clock differential signal input pins
15	MIPI_CLK_P	I	Negative DSI clock differential signal input pins
16	GND	P	Power ground
17	MIPI_D0N	I	Negative DSI Data0 differential signal input pins
18	MIPI_D0P	I	Positive DSI Data0 differential signal input pins
19	GND	P	Power ground
20	MIPI_D3N	I	Negative DSI Data3 differential signal input pins
21	MIPI_D3P	I	Positive DSI Data3 differential signal input pins
22	GND	P	Power ground
23-24	NC	/	/
25	GND	P	Power ground
26-29	NC	/	/
30	GND	P	Power ground
31-32	LEDK	P	Power for LED backlight(Cathode)
33-38	NC	/	/
39-40	LEDA	P	Power for LED backlight(Anode)

I: input, O: output, P: Power, NC or / : No connection

### CTP interface description;

Interface No.	Name	I/O or connect to	Description
1	VCC3V3	P	Power Supply of CTP
2	RST1.8V	I	Reset low
3	SCL1.8V	I	Serial interface clock
4	SDA1.8V	I/O	Serial interface data
5	INT1.8V	O	State change interrupt
6	GND	P	Ground

I: input, O: output, P: Power, NC or / : No connection



## 9. AC CHARACTERISTICS

### TFT Module AC CHARACTERISTICS

#### 7.3.1 Serial Interface Characteristics

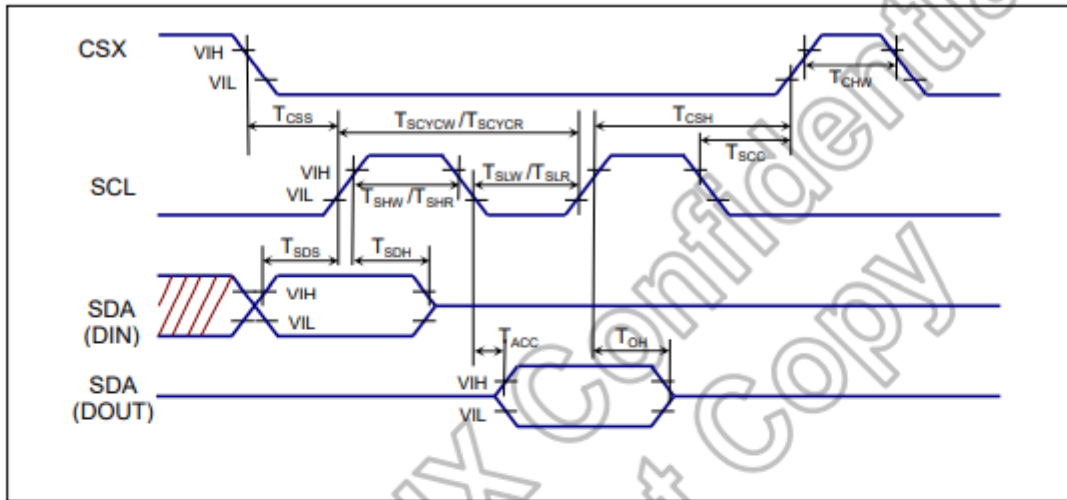


Figure 7.3: Serial Interface Characteristics

(VSSA=0V, IOVCC=1.8V, VCI=2.8V, T<sub>A</sub> = 25°C)

Signal	Symbol	Parameter	Min.	Max.	Unit	Description
CSX	t <sub>css</sub>	Chip select setup time (Write)	15	-	ns	-
	t <sub>css</sub>	Chip select setup time (Read)	60	-		
	t <sub>csh</sub>	Chip select hold time (Write)	15	-		
	t <sub>csh</sub>	Chip select hold time (Read)	65	-		
DCX	t <sub>ast</sub>	Address setup time	0	-	ns	-
	t <sub>ah</sub>	Address hold time (Write/Read)	10	-		
SCL (Write)	t <sub>wc</sub>	Write cycle	66	-	ns	-
	t <sub>wrh</sub>	Control pulse "H" duration	15	-		
	t <sub>wrl</sub>	Control pulse "L" duration	15	-		
SCL (Read)	t <sub>rc</sub>	Read cycle	150	-	ns	-
	t <sub>rdh</sub>	Control pulse "H" duration	60	-		
	t <sub>rdl</sub>	Control pulse "L" duration	60	-		
SDA (Input)	t <sub>ds</sub>	Data setup time	10	-	ns	For maximum C <sub>L</sub> =30pF
	t <sub>dh</sub>	Data hold time	10	-		
SDA (Output)	t <sub>acc</sub>	Read access time	-	100	ns	For minimum C <sub>L</sub> =8pF
	t <sub>oh</sub>	Output disable time	10	-		

**Note:** The input signal rise time and fall time (tr, tf) is specified at 15 ns or less.

Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

Table 7.2: Serial Interface Characteristics

## 7.3.2 DSI Interface Timing Characteristics

### High Speed Mode

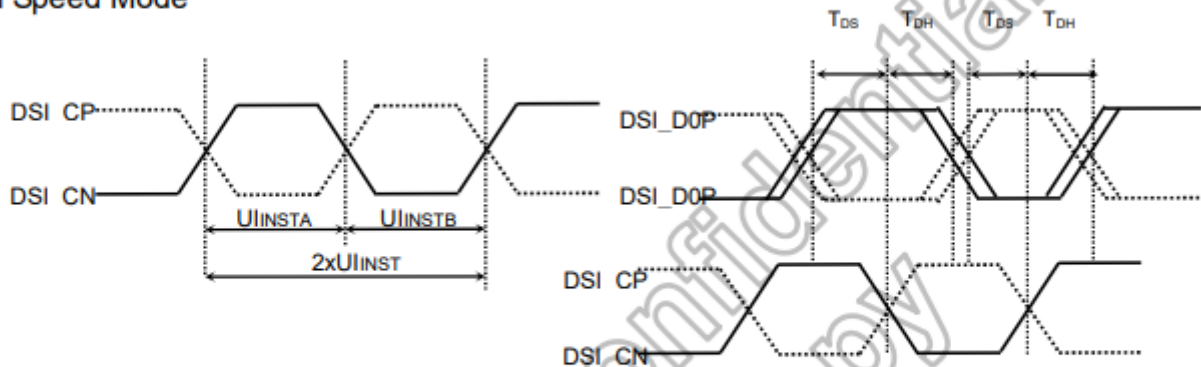


Figure 7.4: DSI clock timing Characteristics

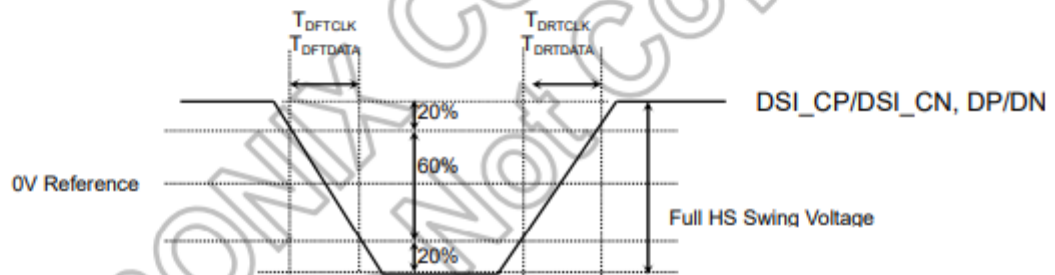


Figure 7.5: Rising and falling time on clock and data channel

(VSSA=0V, IOVCC=1.65V to 3.3V, VCI=2.5V to 3.3V, TA = -30 to 70°C)

Signal	Item	Symbol	Spec.			Unit
			Min.	Typ.	Max.	
DSI_CP/ DSI_CN	Double UI instantaneous	2xUIINST	TBD	-	25	ns
	UI instantaneous	UIINSTA UIINSTB	TBD	-	12.5	ns
DP/DN	Data to clock setup time	TDS	0.15xUI	-	-	ps
	Data to clock hold time	TDH	0.15xUI	-	-	ps
DSI_CP/ DSI_CN	Differential rise time for clock	TDRCLK	150	-	0.3UI	ps
	Differential fall time for clock	TDFCLK	150	-	0.3UI	ps
DP/DN	Differential rise time for data	TDRDATA	150	-	0.3UI	ps
	Differential fall time for data	TDFDATA	150	-	0.3UI	ps

Table 7.3: DSI High Speed Mode characteristics



## Low Power Mode

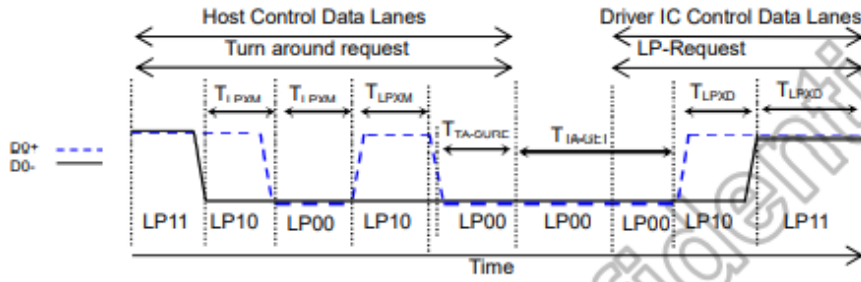


Figure 7.6: BTA from HOST to Display module Timing

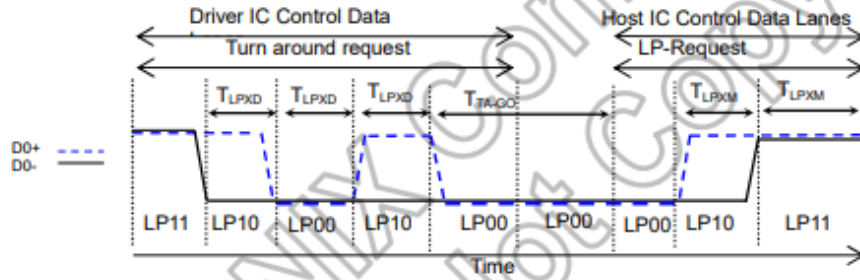


Figure 7.7: BTA from Display module Timing to HOST

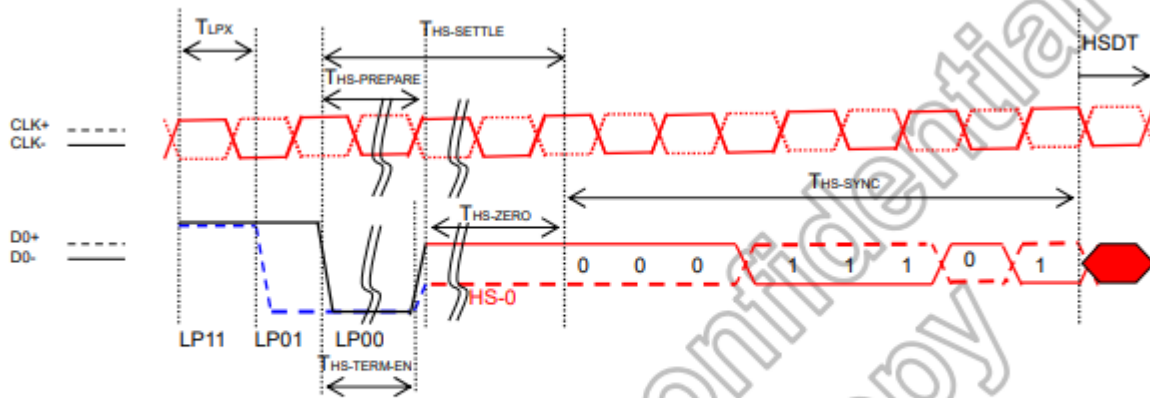
(VSSA=0V, IOVCC=1.65V to 3.3V, VCI=2.3V to 3.3V, TA = -30 to 70°C)

Signal	Item	Symbol	Spec.			Unit
			Min.	Typ.	Max.	
DSI_D0P/ DSI_D0P	Length of LP-00/LP01/LP10/LP11 Host → Display module	T <sub>LPXM</sub>	50	-	-	ns
	Length of LP-00/LP01/LP10/LP11 Display module → Host	T <sub>LPXD</sub>	50	-	-	ns
	Time-out before the MPU start driver	T <sub>TA-SURE</sub>	T <sub>LPXD</sub>	-	2xT <sub>LPXD</sub>	ns
	Time to drive LP-00 by display module	T <sub>TA-GET</sub>	5xT <sub>LPXD</sub>	-	-	ns
	Time to drive LP-00 after turnaround request Host	T <sub>TAGO</sub>	4xT <sub>LPXD</sub>	-	-	ns

Table 7.4: DSI Low Power Mode characteristics

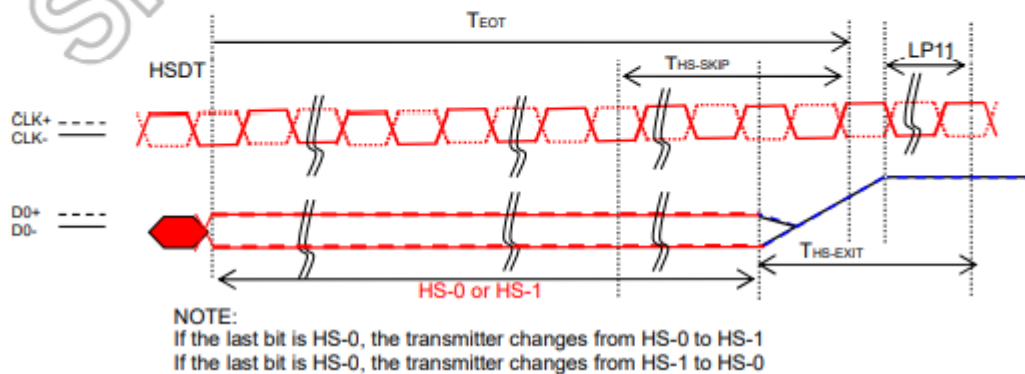


## DSI BURSTS



Signal	Item	Symbol	Spec.			Unit
			Min.	Typ.	Max.	
DSI_D0P/ DSI_D0P	Length of LP-00/LP01/LP10/LP11	T <sub>LPX</sub>	50	-	-	ns
	Time to Driver LP-00 to prepare for HS transmission	T <sub>HS-PREPARE</sub>	40+4UI	-	85+6UI	ns
	Time to enable data receiver line termination	T <sub>HS-TERM-EN</sub>	-	-	35+4xUI	ns
	Time to drive LP-00 by display module	T <sub>TA-GET</sub>	5xT <sub>LPXD</sub>	-	-	ns
	Time to drive LP-00 after turnaround request Host	T <sub>TAGO</sub>	4xT <sub>LPXD</sub>	-	-	ns

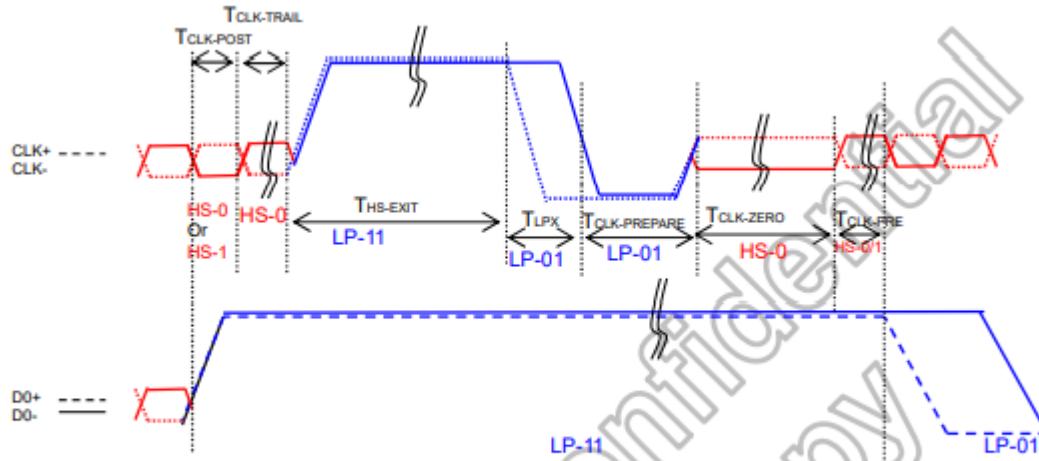
Table 7.5: DSI Low Power Mode to High Speed Mode Timing



Signal	Item	Symbol	Spec.			Unit
			Min.	Typ.	Max.	
DSI_D0P/ DSI_D0P	Time-Out at Display Module to Ignore Transition Period of EoT	T <sub>HS-SKIP</sub>	40	-	55+4xUI	ns
	Time to Driver LP-11 after HS Burst	T <sub>HS-EXIT</sub>	100	-	-	ns

Table 7.6: DSI Low Power Mode to High Speed Mode Timing





Signal	Item	Symbol	Spec.			Unit
			Min.	Typ.	Max.	
DSI_CP/ DSI_CN	Time that the MCU shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode	TCLK-POST	60+52xUI	-	-	ns
	Time to drive HS differential state after last payload clock bit of a HS transmission burst	TCLK-TRAIL	60	-	-	ns
	Time to drive LP-11 after HS burst	THS-EXIT	100	-	-	ns
	Time to drive LP-00 to prepare for HS transmission	TCLK-PREPARE	38	-	95	ns
	Time-out at Clock Lane Display Module to enable HS Termination	TCLK-TERM-EN	-	-	38	ns
	Minimum lead HS-0 drive period before starting Clock	TCLK-PREPARE + TCLK-ZERO	300	-	-	ns
	Time that the HS clock shall be driven prior to any associated data Lane beginning the transition from LP to HS mode	TCLK-PRE	8xUI			

Table 7.7: Clock Lanes High Speed Mode to/from Low Power Mode Timings

### 7.3.3 Reset input timing

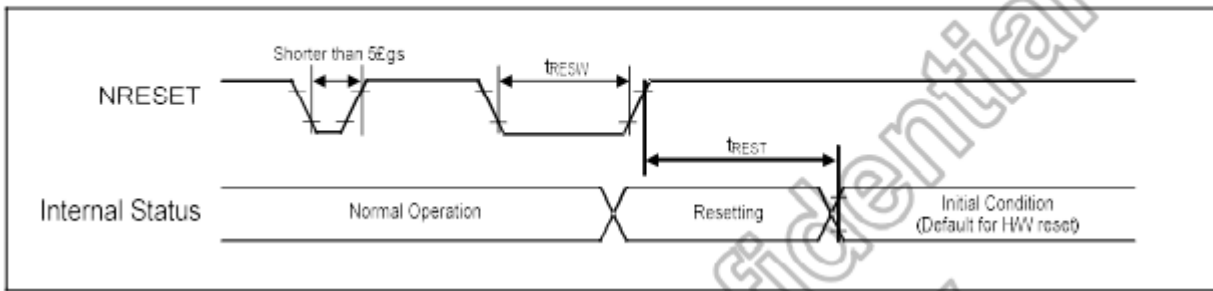


Figure 7.8: Reset input timing

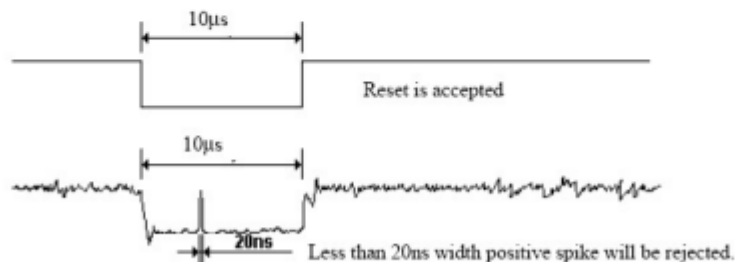
Symbol	Parameter	Related Pins	Spec.			Note	Unit
			Min.	Typ.	Max.		
tRESW	Reset low pulse width <sup>(1)</sup>	NRESET	10	-	-	-	μs
tREST	Reset complete time <sup>(2)</sup>	-	5	-	-	When reset applied during SLPIN mode	ms
		-	120	-	-	When reset applied during SLPOUT mode	ms

Table 7.8: Reset input timing

**Note:** (1) Spike due to an electrostatic discharge on NRESET line does not cause irregular system reset according to the following table.

NRESET Pulse	Action
Shorter than 5 μs	Reset Rejected
Longer than 10 μs	Reset
Between 5 μs and 10 μs	Reset Start

- (2) During the resetting period, the display will be blanked (The display is entering blanking sequence, which Maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode) and then return to Default condition for H/W reset.
- (3) During Reset Complete Time, ID and VCOM value in OTP will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time (tREST) within 5ms after a rising edge of NRESET.
- (4) Spike Rejection also applies during a valid reset pulse as shown as below:



- (5) It is necessary to wait 5msec after releasing NRESET before sending commands. Also Sleep Out command cannot be sent for 120msec.

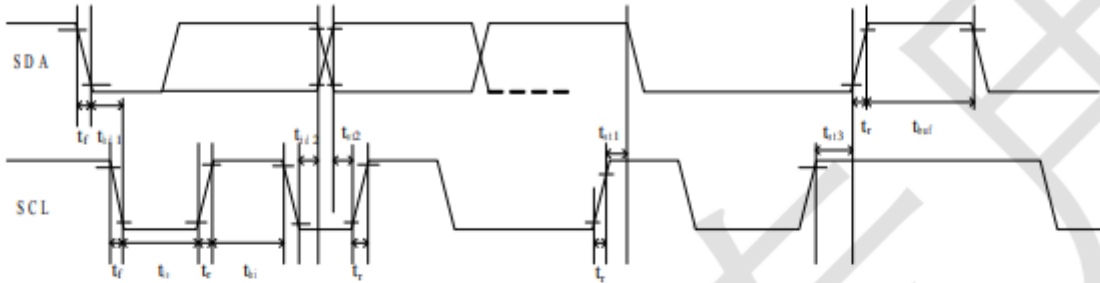




## CTP AC CHARACTERISTICS

Communication speed is 400Kbps or less.

GT9271 provides standard I<sup>2</sup>C interface for communication. In the system, GT9271 always works in slave mode, all communications are initiated by master, and the baud rate can be up to 400K bps. The definition of I<sup>2</sup>C timing is as following:



Test condition1: 1.8V communication interface, 400Kbps, pull up resistor is 2K ohm

Parameter	Symbol	Min.	Max.	Unit
SCL low period	T <sub>lo</sub>	1.3	-	US
SCL high period	T <sub>hi</sub>	0.6	-	US
SCL setup time for START condition	t <sub>st1</sub>	0.6	-	US
SCL setup time for STOP condition	t <sub>st3</sub>	0.6	-	US
SCL hold time for START condition	t <sub>hd1</sub>	0.6	-	US
SDA setup time	t <sub>st2</sub>	0.1	-	US
SDA hold time	t <sub>hd2</sub>	0	-	US

Test condition2: 3.3V communication interface, 400Kbps, pull up resistor is 2K ohm

Parameter	Symbol	Min.	Max.	Unit
SCL low period	T <sub>lo</sub>	1.3	-	US
SCL high period	T <sub>hi</sub>	0.6	-	US
SCL setup time for START condition	t <sub>st1</sub>	0.6	-	US
SCL setup time for STOP condition	t <sub>st3</sub>	0.6	-	US
SCL hold time for START condition	t <sub>hd1</sub>	0.6	-	US
SDA setup time	t <sub>st2</sub>	0.1	-	US
SDA hold time	t <sub>hd2</sub>	0	-	US



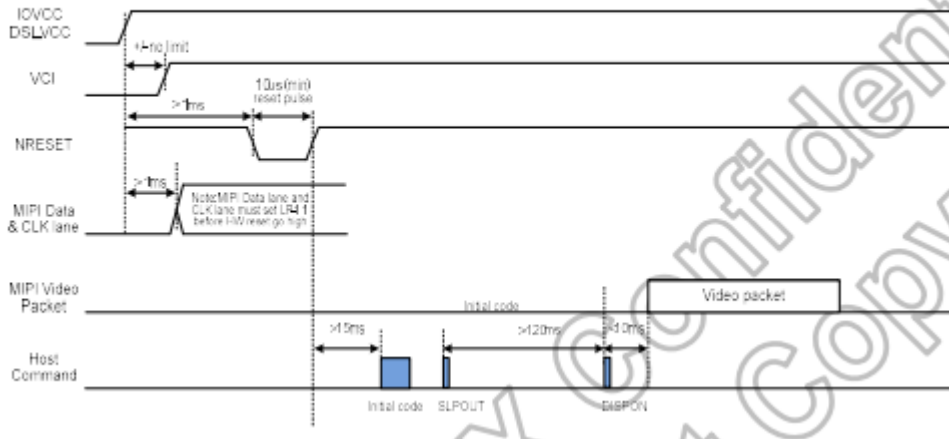
## 10. POWER SEQUENCE

### TFT Module POWER SEQUENCE

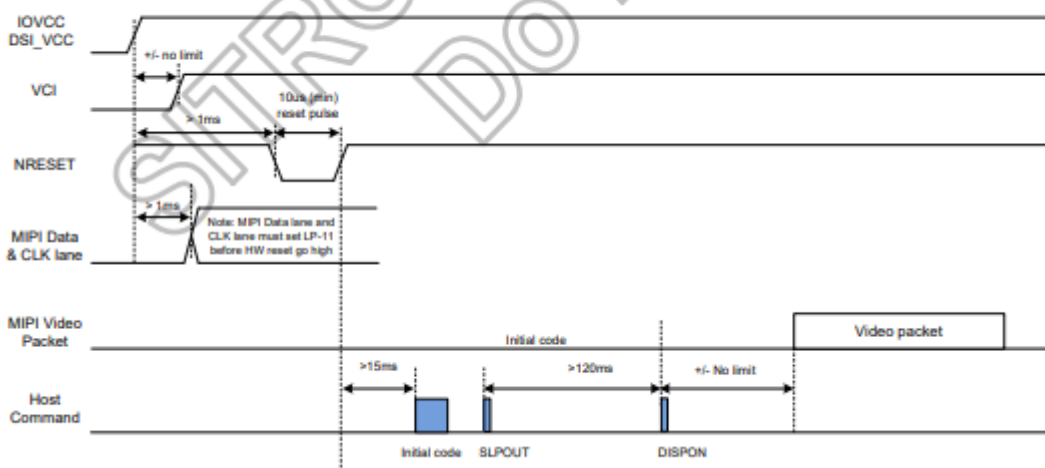
To prevent the device damage from latch up and Improve subjective display effect,the power ON/OFF sequence shown below must be followed.

#### Power on Timing

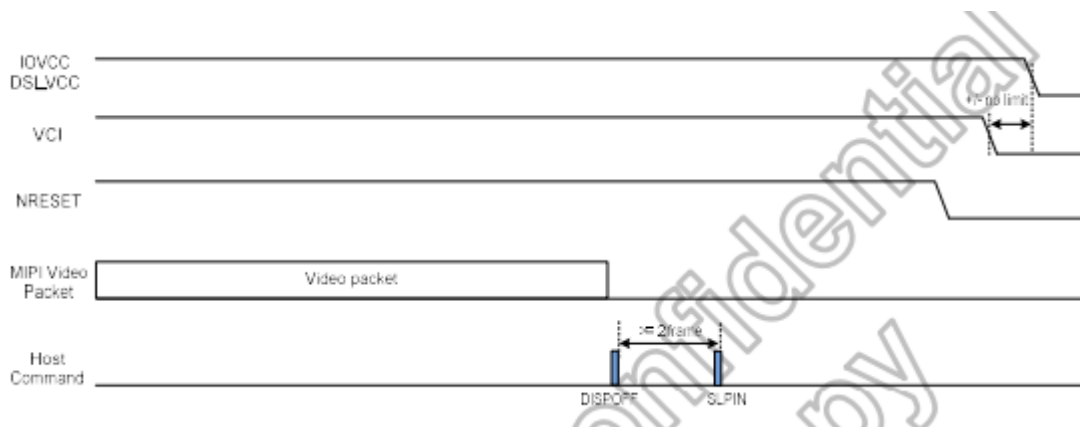
##### ESD\_WHITE\_EN=0



##### ESD\_WHITE\_EN=1

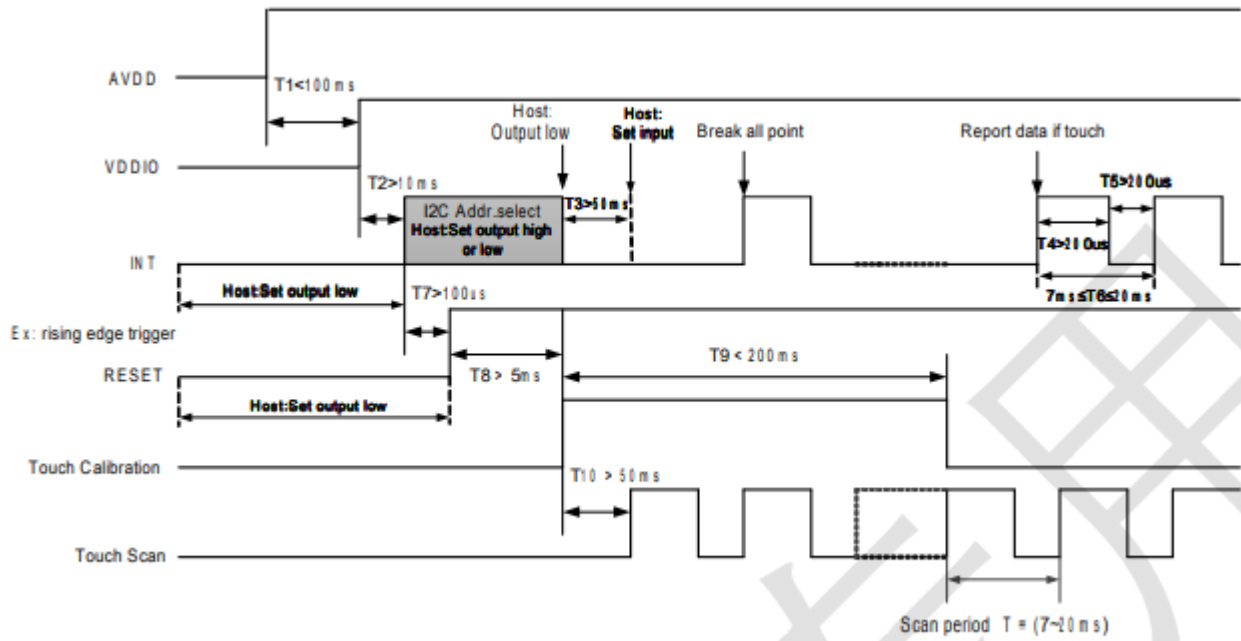


#### Power Off Timing





## CTP POWER SEQUENCE





## 11. RELIABILITY TEST CONDITIONS

No.	Test item	Test condition		Inspection after test
11.1	High temperature storage test	+60℃/120 hours		Inspection after 2~4hours storage at room temperature, the sample shall be free from defects : 1.Current changing value before test and after test is 50% larger; 2. Function defect : Non-display,abnormal-d isplay,missing lines, Short lines,ITO corrosion; 3.Visual defect : Air bubble in the LCD,Seal leak,Glass crack.
11.2	Low temperature storage test	-20℃/120 hours		
11.3	High temperature operating test	+50℃/120 hours		
11.4	Low temperature operating test	-10℃/120 hours		
11.5	Thermal Shock (non-operation )	-20℃ ↔ +60℃/10cycles (30min.)( $\leq$ 30sec.) (30min.)		
11.6	High temperature high humidity test	+60℃*90% RH/120 hours		
11.7	Vibration test for Packaging	Frequency : 250 r/min Amplitude : 1 inch Time: 45min		
11.8	Drop test for Packaging	Drop direction: 1 corner/3 edges/6 sides 10 times		
		Packing weight(kg)	Drop height(cm)	
		$\leq 11$	80 $\pm$ 1.6	
		$11 \leq G \leq 21$	60 $\pm$ 1.2	
		$21 \leq G \leq 31$	50 $\pm$ 1.0	
		$31 \leq G \leq 40$	40 $\pm$ 0.8	
11.9	ESD test	Air discharge: $\pm$ 8KV, 10times Contact discharge: $\pm$ 4KV, 10times		

**Remark :**

- 1.The test samples should be applied to only one test item.
- 2.Sample size for each test item is 3~5pcs.
- 3.For High temperature high humidity test, Pure water(Resistance>10MΩ) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.B/L evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence B/L has.
- 6.Failure judgment criterion: Basic specification, Electrical characteristic, Mechanical characteristic, Optical characteristic.
- 7.After the reliability test, the product only guarantees operation, but don't guarantee all of the cosmetic specification.

## 12. INSPECTION CRITERION

Refer to 《Inspection Criterion for MTP Products-To customer》 , DOCUMENT NO.: AVD(WI)-00-QA-051

## 13. HANDLING PRECAUTIONS

### 13.1 Mounting method

The LCD module consists of two thin glass plates with polarizers which easily be damaged. And since the module is so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

### 13.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent [recommended below] and wipe lightly :

- .Isopropyl alcohol
- .Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent :

- .Water
- .Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated :

- .Soldering flux
- .Chlorine (Cl) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happens by miss-handling or using some materials such as Chlorine (Cl), Sulfur (S) from customer, Responsibility is on customer.

### 13.3 Caution against static charge

The LCD module uses C-MOS LSI drivers, so we recommend that you :

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

### 13.4 Packing

Module employs LCD elements and must be treated as such.

- .Avoid intense shock and falls from a height.
- .To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity.

### 13.5 Caution for operation

- .It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage than the limit causes the shorter LCD life.
- .An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- .Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- .If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- .A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
- .Usage under the maximum operating temperature, 50%Rh or less is required.
- .When fixed patterns are displayed for a long time, remnant image is likely to occur.

### 13.6 Storage

In the case of storing for a long period of time for instance, for years for the purpose of replacement use, the following ways are recommended.

- .Storing in an ambient temperature 10°C to 30°C, and in a relative humidity of 45% to 75%. Don't expose to sunlight or fluorescent light.
- .Storing in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- .Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature

range.

- .Storing with no touch on polarizer surface by the anything else.

It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

### **13.7 Safety**

- .It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- .When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

## **14. PRECAUTION FOR USE**

**14.1** A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

**14.2** On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- .When a question is arisen in this specification.
- .When a new problem is arisen which is not specified in this specifications.
- .When an inspection specifications change or operating condition change in customer is reported to AVD, and some problem is arisen in this specification due to the change.
- .When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

## **15. PACKING SPECIFICATION**

Please consult our technical department for detail information.

## **16. INITIALIZATION CODE**

Please consult our technical department for detail information.

## **17. HSF COMPLIANCE**

- .This products complies with ROHS 2011/65/EU and 2015/863/EU、REACH 1907/2006/EC requirements, and the packaging complies with 94-62-EC.




# AVIDISPLAY

## Work Instruction

### Inspection Criterion for MTP Products --To customer

File No.	AVD (WI) -00-QA-051	Prepared by	
Rev.	V1.1	Checked by	
Pages	18	Customer approval	
Effective date		Control No.	
Controlled Document                      Keeping    Properly			

 <b>AVIDISPLAY</b>		File name	Inspection Criterion for MTP Products	Rev.	V1.0
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## 1. Objective

The CTP test criterion are set to formalize CTP quality standards for AVD with reference to those of the customer for inspection, release and acceptance of finished CTP products in order to guarantee the quality of CTP products required by the customer.

## 2. Scope

This specification is applicable to capacitive touch panel manufactured by AVD.

## 3. Equipment for Inspection

lamp-box、ionizing fan 、10X microscopes 、film card、alcohol/oil ether/acetone、finger cots/[glove](#) vernier caliper、anti-static wrist straps, microcalliper、feeler、pencil hardness tester、spectrophotometer 、drop ball test,etc.

## 4. Sampling Plan and Reference Standards

Sampling plan:Refer to National Standard GB/T 2828.1---2012/ISO2859-1:1999 , level II of normal levels:

Product Category	<a href="#">Consumer</a>	Industrial	Automobile
AQL	<a href="#">MA=0.4 MI=1.5</a>	MA=0.25 MI=0.65	MA=0.15 MI=0.40

## 5. Inspection Conditions and Inspection Reference

5.1. Inspection environment: temperature:  $23\pm3^{\circ}\text{C}$  ; humidity: 40~70%RH; cleanness: 10000 grade;

5.2 .Inspection distance: 30cm $\pm$ 5cm;

5.3. Inspection angle: vertical rotate angle:  $\pm 45^{\circ}$  , up->down;horizontal rotate angle: $\pm 45^{\circ}$  ,left->right

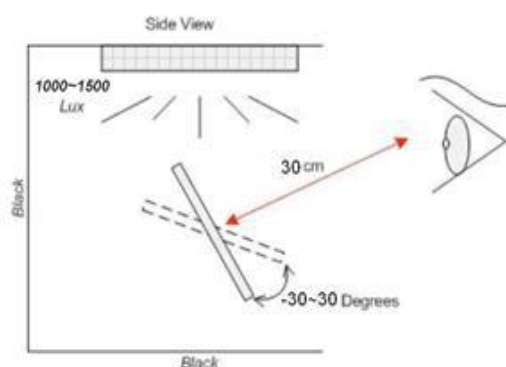
5.4 .Inspection condition:

(1) Inspection luminance is 400~600Lux


5.5 background: white/black

5.6. Inspection time : 10~15s/ pcs;

**Black Booth or Black Background**





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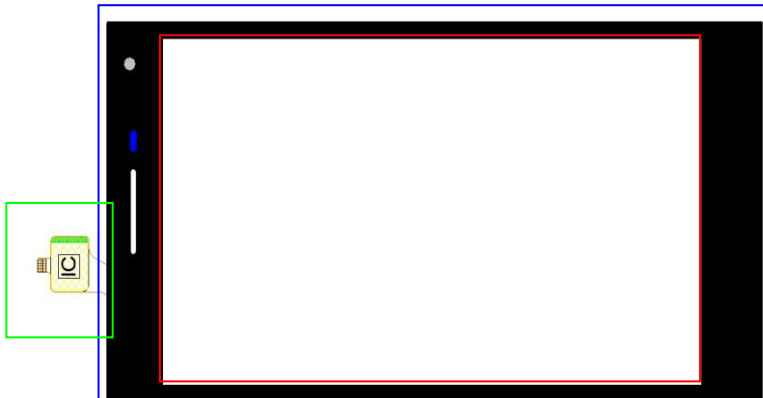
## 5.7 .Area partition:

5.7.1 AA area: Active area;

5.7.2 VA area: Visual Windows area (refer to below sketch Red blank);

5.7.3 Area A: visual area from front side view((refer to below sketch Blue blank))

5.7.4 Area B: four sides and FPC area((refer to below sketch Green blank))



5.7.5 Undefined items or other special items, refer to mutual agreement and limited sample.If criterion does not match product specifications/ technical requirement, both should be subject to special inspection criterion agreed by customer.

## 5.8 Defect define:

5.8.1 Defect in AA area: pixel defect, function defect (no display, miss line , dark line, wrong polarizer angle, image retention, flicker, abnormal display, dim/bright display, Contrast ratio, dot defect(white dot, black dot, dark dot, Convex-concave point, bubble, foreign material), visual line defect(fiber, scratch, foreign material) , stain and so on

5.8.2 Defect in VA area: dot defect(white dot, black dot, dark dot, Convex-concave point, bubble, foreign material), visual line defect(fiber, scratch, foreign material) , stain and so on

5.8.3 Defect in A area: Line defect (scratch、soft flocks、fibre) 、 dot defect (white dot、 black dot、 same color dot、 different color dot、 dust、 bubble) 、 surface stain、 pin-hole、 light leak、 scratch.

5.8.4 Defect in B area: Broken、 crack/chipping、 FPC defect

5.9 Undefined items or other special items, refer to mutual agreement and limited sample. If criterion does not match product specifications/ technical requirement, both should be subject to special inspection criterion agreed by customer.


5.10.To the touch screen and display size of different products: : The defects of TFT screen are determined according to the corresponding TFT screen size. ; The defects in TP VA area are determined according to the corresponding criteria of the corresponding VA area, and the outside of the VA area is determined by the dimension standard.

## 6. Defects and Acceptance Standards

### 6.1 Function defect for TP

#### 6.1.1 Electrical properties test

Check in AVD tester. The program will release result automatically. There are “OK”、 “PASS” 、

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“NG”and the final judgment must be“OK”“PASS”,and we need to pass the draw line test.


Refer to 《\*\*serise IC test program》

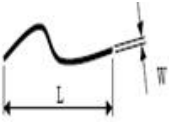
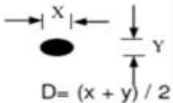
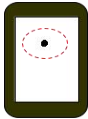
No.	Defects	Descriptions	Accepted standard	MAJ	MIN
6.1.1	Short	Measured data has much difference compared with normal;line is not stable	Reject	√	
6.1.2	Open	Measured data has no change.Line is open	Reject	√	
6.1.3	No reaction	No reaction and there is no line in screen	Reject	√	
6.1.4	Abnormal display	Screen has display but line is open or bent	Reject	√	
6.1.5	Button no reaction	Press the button but no reaction	Reject	√	
6.1.6	Button not correct	Press the button .Reaction is not stable	Reject	√	

## 6.2 Appearance inspection


### 6.2.1 Normal lens dot/line defect

#### 6.2.1.1.Industrial product point/line standard

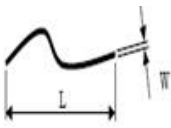
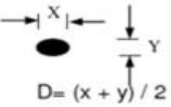
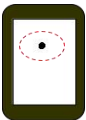
 <b>AVIDISPLAY</b>		File name	Inspection Criterion for MTP Products	Rev.	V1.0
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Defect	≤5"	5~10"	10~15"	>15"	Accepted standard	MAJ	MIN
S/C,line defect W:width L:length 	Tactile S/C->NG	Tactile S/C->NG	Tactile S/C->NG	Tactile S/C->NG	Reject		√
	W≤0.05mm, ->OK; Density is high ->NG	W≤0.05mm, ->OK; Density is high ->NG	W≤0.05mm, ->OK; Density is high ->NG	W≤0.08mm, ->OK; Density is high ->NG	Accept		√
	0.05mm<W≤0.10mm, L≤8mm quantity≤3 distance>10mm	0.05mm<W≤0.1mm, L≤10mm quantity≤6 distance>10mm	0.05mm<W≤0.1mm, L≤20mm quantity≤5 distance>10mm	0.08mm<W≤0.1mm, L≤25mm quantity≤5 distance>10mm	Accept		√
	W>0.10mm L>8mm	W>0.1mm L>10mm	W>0.1mm L>20mm	W>0.1mm L>25mm	Reject		√
Dot defect D:Diameter  	D≤0.15mm, ->OK;	D≤0.15mm, ->OK;	D≤0.20mm, ->OK;	D≤0.30mm, ->OK;	Accept		√
	0.15mm<D≤0.25mm quantity≤3 0.25mm<D≤0.3mm quantity≤1 distance>10mm	0.15mm<D≤0.30mm quantity≤3 0.30mm<D≤0.40mm quantity≤1 distance>10mm	0.20mm<D≤0.50mm quantity≤5 distance>10mm	0.30mm<D≤0.50mm quantity≤5 distance>10mm	Accept		√
	D>0.30mm	D>0.40mm	D>0.50mm	D>0.50mm	Reject		√


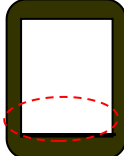
Note: within 1 mm, if there are more than three (round shape), two (linear) or round shape and line shape, it is called density;


 <b>AVIDISPLAY</b>		File name	Inspection Criterion for MTP Products	Rev.	V1.0
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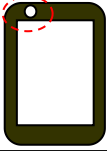
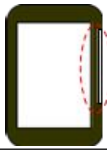



#### 6.2.1.2. Non-industrial product dot/line standard


Defect	≤5"	5~10"	10~15"	>15"	Accepted standard	MAJ	MIN
<b>S/C ,line defect</b> W:width L:length 	Tactile S/C->NG	Tactile S/C->NG	Tactile S/C->NG	Tactile S/C->NG	Reject		√
	W≤0.03mm, ->OK; Density is high ->NG	W≤0.05mm, ->OK; Density is high ->NG	W≤0.05mm, ->OK; Density is high ->NG	W≤0.05mm, ->OK; Density is high ->NG	Accept		√
	0.03mm< W≤0.08mm, L≤5mm quantity≤2	0.05mm< W≤0.1mm, L≤8mm quantity≤3	0.05mm< W≤0.1mm, L≤10mm quantity≤3	0.05mm< W≤0.1mm, L≤20mm quantity≤5	Accept		√
	W>0.08mm L>5mm	W>0.1mm L>8mm	W>0.1mm L>10mm	W>0.1mm L>20mm	Reject		√
<b>Dot defect</b> D:Diameter  	D≤0.10mm, ->OK;	D≤0.15mm, ->OK;	D≤0.15mm, ->OK;	D≤0.2mm, ->OK;	Accept		√
	0.10mm<D≤0.2mm quantity≤2 0.2<D≤0.25, quantity≤1 distance>10mm	0.15mm<D≤0.25mm quantity≤3 0.25<D≤0.3 quantity≤1 distance>10mm	0.15mm<D≤0.30mm quantity≤3 0.30mm<D≤0.40mm quantity≤1 distance>10mm	0.20mm<D≤0.50mm quantity≤5 distance>10mm	Accept		√
	D>0.25mm	D>0.30mm	D>0.40mm	D>0.50mm	Reject		√
Note: the scratches, lines, and points are all density and rejected (two or more in 10mm are called density);							

#### 6.2.2. Normal lens (thickness < 1.8mm, surface without AG/AR treatment)Screen printing standard

Defect	Description	Accepted standard	MAJ	MIN
<b>Printing sawtooth</b> 	sawtooth width which is almost the same with VA area W≤0.15mm	Accept		√
	sawtooth width which is almost the same with VA area W>0.15mm	Reject		√
<b>Wire mark</b> 	≤0.15mm	Accept		√
	>0.15mm	Reject		√

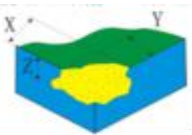
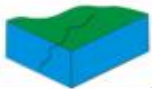
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<b>Ink pinhole</b> 	Invisible with reflector light	Accept		√
<b>Ink film defect</b>	Ink film:s/c、soft flocks、fibre Ink film stain/color shift:refer to limited sample Ink film foreign material/scratch: refer to 6.1.1 visible area judgment	Accept		√
<b>Ink light leak</b> 	LENS thickness≤0.7mm: The leakage width of the edge area ≤0.15mm , Unilateral light-leaking≤1 LENS thickness>0.7mm: The leakage width of the edge area≤0.25mm , Unilateral light-leaking≤1	Accept		√
<b>Ink color shift</b>	Refer to limited sample			√
<b>font、glass silver line (ink area) width≥0.2mm</b> 	D≤0.20mm; N≤2 ↑	Accept		√
	D>0.20mm	Reject		√
	Refer to limited sample, if it's out of spec	Reject		√
<b>word/color error</b>	Word or color or position is different from drawing and sample.	Reject	√	
<b>word missing width≤0.2mm</b> 	height, a≤1/4h, width≤1/2w	Accept		√
<b>Font thickness different and color nonuniform</b> 	Refer to limited sample, if it's out of spec	Reject		√
<b>IR/video/Receive hole /Button hole</b>	Irregular hole , offside, refer to drawing	Accept		√
	Foreign material/scratch exist in hole,refer to 6.1.1	Reject		√

 <b>AVIDISPLAY</b>		File name	Inspection Criterion for MTP Products	Rev.	V1.0
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<b>LENS broadside foreign material</b>	Width $\leq$ 0.15mm	Accept		√
<b>Ink spill</b>	LENS broadside or receive hole or button hole have ink spill defect, refer to limited sample.	Accept		√

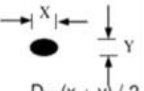
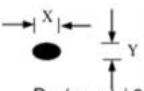
### 6.2.3 Normal lens breakdown standard


Defect	$\leq 5''$	5~10''	10~15''	>15''	Accepted standard	MAJ	MIN
<b>LENS breakage</b> 	X $\leq$ 0.3mm, Y $\leq$ 0.3mm, one side $\leq$ 1	X $\leq$ 0.3mm, Y $\leq$ 0.4mm, one side $\leq$ 1	X $\leq$ 0.4mm, Y $\leq$ 0.4mm, one side $\leq$ 1	X $\leq$ 0.5mm, Y $\leq$ 0.5mm, one side $\leq$ 1	Accept		√
	X>0.3mm, Y>0.3mm	X>0.3mm, Y >0.4mm	X>0.4mm, Y>0.4mm	X>0.5mm, Y>0.5mm	Reject		√
<b>Sensor breakage</b>	Not affect ITO line, not lengthen,function test is OK And be non-visual after attaching Lens				Accept		√
	affect ITO line and be visual				Reject		√
<b>Glass crack</b> 	Crack lengthen to outside				Accept		√
	Crack lengthen to inside				Reject		√

### 6.2.4 special lens standard

#### 6.2.4.1 AG/AR/AF processing LENS standard

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Thick ness	Defect type	S <5 inch	5≤S< 10 inch	10≤S< 15 inch	15 inch≤S	criterion
thickn ess< 1.8m m	Scratch: W: width, L: length	W≤0.05, Ignore, dense except	W≤0.05, Ignore, dense except	W≤0.05, Ignore, dense except	W≤0.05, Ignore, dense except	accept
		0.05mm< W≤0.1mm, L≤12mm, N≤3	0.05mm< W≤0.1mm, L≤15mm, N≤3	0.05mm< W≤0.1mm, L≤20mm, N≤4	0.05mm< W≤0.1mm, L≤25mm, N≤5	accept
		0.1mm< W≤0.15mm, L≤12mm, N≤2	0.1mm< W≤0.15mm, L≤15mm, N≤2	0.1mm< W≤0.15mm, L≤20mm, N≤3	0.1mm< W≤0.15mm, L≤25mm, N≤4	accept
		W>0.15mm, L>12mm	W>0.15mm, L>15mm	W>0.15mm, L>20mm	W>0.15mm, L>25mm	reject
	Dot:D:diameter  $D = (x + y) / 2$	D<0.2mm,ignore, dense except	D<0.2mm,ignore, dense except	D<0.2mm,ignore, dense except	D<0.2mm,ignore, dense except	accept
		0.2mm≤D<0.3mm, N≤3	0.2mm≤D<0.3mm, N≤3, 0.3mm≤D<0.4mm, N≤1	0.2mm≤D<0.4mm, N≤3 0.4mm≤D<0.5mm, N≤1	0.2mm≤D<0.4mm, N≤3 0.4mm≤D<0.6mm, N≤2	accept
		Note: point defect,the diameter is based on the etching defect , not including the ripple marks on the etching defect				
thickn ess≥ 1.8m m	Scratch: W: width, L: length	W≤0.05, Ignore, dense except	W≤0.05, Ignore, dense except	W≤0.05, Ignore, dense except	W≤0.05, Ignore, dense except	accept
		0.05mm< W≤0.1mm, L≤12mm, N≤3	0.05mm<W≤0.1mm, L≤15mm, N≤3	0.05mm<W≤0.15mm, L≤20mm, N≤4	0.05mm<W≤0.2mm, L≤25mm, N≤5	accept
		0.1mm< W≤0.15mm, L≤12mm, N≤2	0.1mm<W≤0.2mm, L≤15mm, N≤2	0.15mm<W≤0.25mm, L≤20mm, N≤2	0.2mm<W≤0.3mm, L≤25mm, N≤2	accept
	Dot:D:diameter  $D = (x + y) / 2$	D<0.2mm,Ignore, dense except	D<0.2mm,Ignore, dense except	D<0.2mm,Ignore, dense except	D<0.2mm,Ignore, dense except	accept
		0.2mm≤D<0.3mm, N≤3	0.2mm≤D<0.3mm, N≤3 0.3mm≤D<0.4mm, N≤1	0.2mm≤D<0.4mm, N≤3 0.4mm≤D<0.5mm, N≤2	0.2mm≤D<0.4mm, N≤3 0.4mm≤D<0.6mm, N≤3	accept
		D≥0.3mm	D≥0.4mm	D≥0.5mm	D≥0.6mm	reject
		Note: point defect,the diameter is based on the etching defect , not including the ripple marks on the etching defect				
All the thickn ess	Edge breakage	X ≤0.5 mm Y≤0.5 mm Z≤ 1/2 T One-sided only allows 1	X ≤0.5 mm Y≤0.5 mm Z≤ 1/2 T One-sided only allows 1	X ≤0.5 mm Y≤0.5 mm Z≤ 1/2 T One-sided only allows 2	X ≤0.5 mm Y≤0.5 mm Z≤ 1/2 T One-sided only allows 2	accept


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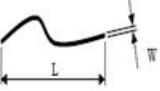
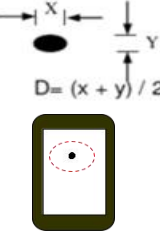
Corner breakage	$X \leq 0.5 \text{ mm}$ $Y \leq 0.5 \text{ mm}$ $Z \leq 1/2 T$ , unilateral allowable: $N \leq 1$ ;
Glass crack	The crack is extended to the outer edge and is calculated according to the collapse; Progressive cracks extending to the inner edge are not allowed
Sand edge	$W \leq 0.3 \text{ mm}$ , ignore; $W > 0.3 \text{ mm}$ , reject
Sawtooth	The width of the sawtooth near the VA area : $W \leq 0.3 \text{ mm}$ , allow, $W > 0.3 \text{ mm}$ , reject;
Main color ink light leak	Edge area leakage width : $W \leq 0.25 \text{ mm}$ Only unilateral leakage is allowed; Edge area leakage width $> 0.25 \text{ mm}$ reject
Screen printing	$W \leq 0.15 \text{ mm}$ , allow, $W > 0.15 \text{ mm}$ , reject
Main color ink pinhole	Outside the 2mm edge of the VA area. Reflection conditions check for invisible permission, Any pinholes are not allowed within 2mm of the area of the VA area
Defects in the main color ink layer	The ink layer has fiber, impurity reference visual area standard; Standards for scratch within the ink layer: $0.05 \text{ mm} < W \leq 0.08 \text{ mm}$ , $L \leq 3 \text{ mm}$ , $N \leq 1$ , allow; $W > 0.08 \text{ mm}$ , $L > 3 \text{ mm}$ , reject
Ink pattern spillage	$D \leq 0.15 \text{ mm}$ ; $N \leq 2$ , allow; $D > 0.15 \text{ mm}$ , reject
Ink pattern gap	Gap width $\leq 1/4 h$ (h is the height of the pattern) or gap width $\leq 1/2 w$ (w is the width of the pattern) allow
Dirty mark	Printing main color stain $W \leq 0.3 \text{ mm}$ ignore, Not visible under fluorescent lamps, allow; Printing main color stain $W > 0.3 \text{ mm}$ , visible under fluorescent lamps, reject
IR semi-permeable area ink pinhole	$D \leq 0.15 \text{ mm}$ , $N \leq 1$ , allow; $D > 0.15 \text{ mm}$ , reject;
IR semi-permeable area ink color difference	Reflector is not visible in black background, acceptable
IR semi-permeable area ink internal impurities	$D \leq 0.35 \text{ mm}$ ; $N \leq 5$ , allow; $D > 0.35 \text{ mm}$ ; $N > 5$ , reject
Dander foreign body	$W \leq 0.3 \text{ mm}$ , $L \leq 10 \text{ mm}$ , $N \leq 3$ , allow; $W > 0.3 \text{ mm}$ , reject ;
Appearance	The surface is attached to a slight wipes smudge acceptable, and the air gun can be blown off of the dandruff acceptable
AG/AR Glass color difference	Refer to the technical signature


Note: 5 or more defects within 10mm are called intensive. (intensive defects: not allowed). The spacing of all defects is 10mm

6.2.4.2 Lens thickness is greater than or equal to 1.8mm product(with/without ink printing)




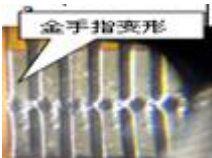

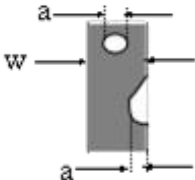
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Defect	≤5"	5~10"	10~15"	>15"	Accepted standard
S/C , line defect W:width L:length 	W≤0.08 ignore except dense		W≤0.1 ignore except dense		accept
	0.08<W≤0.15 L≤18 mm; N≤3 0.15<W≤0.3 L≤18; N≤2	0.08<W≤0.15 L≤20mm; N≤3 0.15<W≤0.3 L≤20mm; N≤3	0.1<W≤0.2 L≤25mm; N≤4 0.2<W≤0.5 L≤25mm; N≤3	0.1<W≤0.2 L≤30mm; N≤5 0.2<W≤0.5 L≤30mm; N≤4	accept
	W>0.3, L>18	W>0.3, L>20	W>0.5mm, L>25mm	W>0.5mm, L>30mm	reject
Dot defect D:Diameter 	D≤0.2mm Ignore, except dense	D≤0.2mm Ignore, except dense	D≤0.3mm Ignore, except dense	D≤0.3mm Ignore, except dense	accept
	0.2<D≤0.25, N≤2	0.2<D≤0.5, N≤5	0.3<D≤0.8, N≤5	0.3<D≤0.8, N≤6	accept
	D>0.25mm	D>0.50mm	D>0.80mm	D>0.80mm	reject
Side damage	X ≤0.5 mm Y≤0.5 mm Z≤1/2 T Unilateral:N≤1	X ≤0.5 mm Y≤0.5 mm Z≤1/2 T Unilateral:N≤1	X ≤0.5 mm Y≤0.5 mm Z≤1/2 T Unilateral:N≤2	X ≤0.5 mm Y≤0.5 mm Z≤1/2 T Unilateral:N≤2	accept
Angle damage	X ≤0.5 mm Y≤0.5 mm Z≤1/2 T, Unilateral:N≤1				accept
Glass crack	The crack is extended to the outer edge and is calculated according to the collapse; Progressive cracks extending to the inner edge are not allowed				
Sand edge	W≤0.25mm , ignore; W>0.25mm , reject				
Sawtooth	The width of the sawtooth near the VA area : W≤0.3mm , allow, W>0.3 mm , reject;				
Main color ink light leak	Edge area leakage width : W≤0.25mm Only unilateral leakage is allowed; Edge area leakage width >0.25mm reject				
Screen printing	W≤0.15mm , allow, W>0.15mm , reject				
Main color ink pinhole	Outside the 2mm edge of the VA area, Reflection conditions check for invisible permission, Any pinholes are not allowed within 2mm of the area of the VA area				
Defects in the main color ink layer	The ink layer has fiber, impurity reference visual area standard; Standards for scratch within the ink layer: 0.05mm<W≤0.08mm, L≤3mm,N≤1, allow; W>0.08mm, L>3mm, reject				
Ink pattern spillage	D≤0.15mm; N≤2, allow; D>0.15mm , reject				
Ink pattern gap	Gap width≤1/4h (h is the height of the pattern) or gap width≤1/2w (w is the width of the pattern) allow				
Dirty mark	Printing main color stain W≤0.3mm ignore, Not visible under fluorescent lamps, allow; Printing main color stain W>0.3mm, visible under fluorescent lamps, reject				
IR semi-permeable area ink pinhole	D≤0.15mm, N≤1, allow; D>0.15mm, reject;				
IR semi-permeable area ink color difference	Reflector is not visible in black background, acceptable				

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IR semi-permeable area ink internal impurities	$D \leq 0.35\text{mm}$ ; $N \leq 5$ , allow; $D > 0.35\text{mm}$ ; $N > 5$ , reject
Note: 1. 5 or more defects within 10mm are called intensive. (intensive defects: not allowed). The spacing of all defects is 10mm 2. inspection distance: $750 \pm 50\text{mm}$ , if appearance is invisible, ignore	

### 6.2.5 . FPC defect

Defect	Description	Accepted standard	MAJ	MIN
<b>FPC folding</b> 	FPC is folding and can not restore-> Reject FPC is folding and can restore->compare with limited sample	Reject		√
<b>FPC cover layer defect</b>	FPC cover layer peeling off	Reject		√
<b>FPC color shift and bubble</b>	PI layer have color shift or bubbled due to high welding temperature or long welding time.	Reject		√
<b>Golden finger defect</b> 	peeling off、bonding deformed、glue remained、oxidized, stained	Reject		√
<b>Joggle defect</b> 	bent, broken, peeling off	Reject		√
<b>FPC defect</b> 	(golden finger) dented, pin hole $a \leq w/3$	Accept		√
	open/scratch/cracked/Gold finger has glue/FPC surface has glue accumulation	Reject		√
	oxidized, stained	Reject		√
<b>FPC loophole</b>	In the protected line area Or not affecting normal lines, The soft batch $\leq 2.5\text{ mm}$ , accept , Hard board (PCB, PC, steel sheet reinforcing plate)The soft batch $\leq 1.0\text{mm}$ Or less than half of the edge of the wire to the edge (Take a smaller value)	Accept		√


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#### 6.2.6. Attaching defect (protective film/adhesive tape/foam/PC...)

Defect	Description	Accepted standard	MAJ	MIN
<b>High temperature glue paper</b>	1.Glue paper attached in FPC doesn't cover component or FPC cove layer. 2.Glue paper attached in golden finger doesn't cover golden finger or peel off	Reject		√
<b>Protective film</b>	Clean、attaching flat、no shifting or bubble	Accept		√
	Protective film attaching bubble in VA: D≤2.0mm N≤5 distance≥20mm	Accept		√
	Protective film attaching bubble in VA: D>2.0mm N>5 distance<20mm	Reject		√
<b>Tape</b>	Attach position refer to the drawing	Accept		√
<b>Foam</b>	1. Follow the drawings first 2. If the drawings are not specified in size, refer to the following requirements Gap spec:0.5+/-0.5mm, foam must be smaller than sensor edge side and can not enter into VA.	Accept		√
<b>PC board/ adhesive tape</b>	Tape must be smaller than LENS edge side and can not be folding ,dent or shifting.Do not obstruct the hole;	Accept		√
<b>Anti-explosion fim/Anti-glare film/blue film/AG film</b>	Impression print refer to the limited sample	Accept		√
	Attach position refer to the drawing	Accept		√
	The bubbles are not allowed in the OCA rubber layer, and the bubbles are ignored between the lens and the AG layer or the explosion-proof film layer	Accept		√

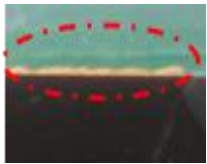
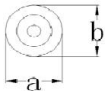
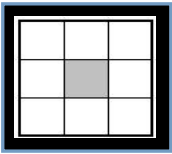
#### 6.2.7. Metal frame (Metal Bezel)

No.	Item	Description	Accepted criterion	MAJ	MIN
6.2.7.1	Material & surface treatment	Metal frame/surface treatment do not conform to the specifications.	Rejected	√	
6.2.7.2	Tab twist Unconformity/ Tab not twisted	Wrong twist method or direction and twist tabs are not twisted as required.	Rejected	√	
6.2.7.3	Bezel paint loss	Scratch/paint loss/Bezel surface concave-convex dot/dent	1.Front surface: Paint peel off and scratch to the bottom Dot:D≤0.5mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm exceeds 2;	√	
6.2.7.4	Bezel scratch		2.Front dent, air bubble and side with paint peeling off scratch to the bottom Dot: D≤1.0mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm, exceeds 2;	√	
6.2.7.5	Painting peel off, discoloration,dent, and scratch			√	

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6.2.7.6	Burr	Burr(s) on metal bezel is so long as to get into viewing area.	Rejected	√	
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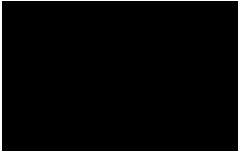
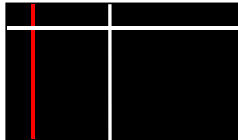
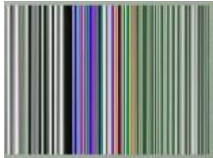
#### 6.2.8. Others

Defect	Description	Accepted standard	MAJ	MIN
<b>Glue flow</b> 	Insulation oil flow in VA area	Reject		√
	ACF/insulation oil flow in VA area	Reject		√
	Sensor edge side glue flow	Accept		√
<b>IC/FPC gap glue</b>	FPC gap glue:cover FPC connect point totally IC glue: cover IC line connect totally	Accept		√
	Glue height : follow the technology spec	Accept		√
<b>Newton circles (rainbow)</b> 	Circles quantity> 2	Reject		√
<b>Layering</b>	LENS/Sensor layering	Reject	√	
<b>Surface</b>	Stain defect which can be removed by cleaning solvent and cloth Defect quantity≤10% Lot total quantity->Accept Remark: defect product which is sorted out by AQL is not included in the 10% part.Unmovable stain refer to 6.1.1 specification.	Reject		√
Isolation point  VA diagram	Gray area In 8X8mm area, all isolation points are missing	Reject		√
	White area In 15X15mm area,all isolation points are missing	Reject		√
	5mm within VA (black area) , isolation points missing ->Ignored	Accept		√
	Isolation points are overlaid	Accept		√

### 6.3 .Function inspection standard for TFT-LCM final goods


#### 6.3.1 normal defect in TFT screen

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Defects	Inspection Criterion	Pictures	Inspection method/tools	Defect category
No display /reaction	shows no picture/display in normal connected situation. ->Rejected		Naked eyes/ testers	MA
Missing segment	Shows missing lines in normal display		Naked eyes/ testers	MA
Image retention (sticking)	<a href="#">No Image retention During AVD Functional test process, condition: 25°C, AVD test images</a>	<a href="#">AVD test images</a>	Naked eyes/ testers	MA
Display abnormal	Not accepted		Naked eyes/ testers	MA
Display dim/bright	Refer to limited sample	/	Naked eyes/ limited sample	MA
Contrast	<a href="#">Refer to AVD specification</a>	/	Naked eyes/ limited sample	MA
White dot	Refer to dot criterion	/	Naked eyes	MI
White speckle	Refer to limited sample	/	Naked eyes/ limited sample	MI
Yellow speckle	Refer to limited sample	/	Naked eyes/ limited sample	MI

### 6.3.2 LCD pixel dot defect in TFT screen (defect category: MI)


Item	Inspection criterion			
Size	S < 5"	5 ≤ S < 10"	10 ≤ S < 15"	> 15"

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Item	Inspection criterion			
Color pixel dot defect(RGB dot)	1	2	2	3
2 connected bright dot	0	0	1	1
3 connected bright dot or more	0	0	0	0
Bright dot total quantity	1	2	3	4
Random dark dot quantity	2	3	4	5
2 connected dark dot	1	1	2	2
3 connected dark dot or more	0	0	0	0
Dark dot total quantity	3	4	5	6
Multi-bright dot	ND 5 % hidden, OK			
Remark: 2 bright dots distance DS≥15mm 2 dark dots distance DS≥5mm				
1) Bright dot: Power on TFT and RGB dot in black display				
2) Dark dot: Power on TFT and gray or black dot in RGB display				
3) Multi-bright dot: Power on TFT and fluorescent tiny dot in black display(only visible in black display)				

### 6.3.3 Metal frame (Metal Bezel)

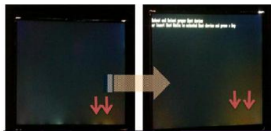
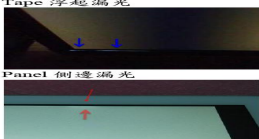
Item	Description	Accepted criterion	MAJ	MIN
Material & surface treatment	Metal frame/surface treatment do not conform to the specifications.	Rejected	√	
Tab twist Unconformity/ Tab not twisted	Wrong twist method or direction and twist tabs are not twisted as required.	Rejected	√	
Bezel paint loss	Scratch/paint loss/Bezel surface concave-convex dot/dent	1.Front surface: Paint peel off and scratch to the bottom Dot:D≤0.5mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm exceeds 2; 2.Front dent, air bubble and side with paint peeling off scratch to the bottom Dot: D≤1.0mm, exceeds 3; Line:L≤3.0mm,W≤0.05mm, exceeds 2;	√	
Bezel scratch			√	
Painting peel off, discoloration,dent, and scratch			√	
Burr	Burr(s) on metal bezel is so long as to get into viewing area.	Rejected	√	


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### 6.3.3 Backlight components

Item	Description	Accepted criterion	MAJ	MIN
No backlight wrong Color	/	Rejected	√	
Color deviation	When powered on, the LCD color differs from its sample and found that the color not conforming to the drawing after testing.	Refer to sample and drawing.		√
Brightness deviation	When powered on, the LCD brightness differs from its sample and is found after testing not conforming to the drawing; or if it conforms to the drawing but the brightness over $\pm 40\%$ than its typical value.	Refer to sample and drawing.		√
Uneven brightness	Uneven on the same LCD and out of the specification of the drawing. The no specification evenness= (the max value-the min value)/ mean value $< 70\%$ .	Refer to sample and drawing.		√
Spot/line /scratch	When power on, it has dirty spot, scratches and so on spot and line defects.	Refer to dot/line standard		√

### 6.3.4. Others

Item	Description	Accepted criterion	MAJ	MIN
Assembly foreign material	Dot/linear stain after assembly backlight and diffuse film TP assembly foggy stain	Invisible when power on->OK Refer to 6.1.1 dot/line spec		√
Product mark	Missing, unclear, incorrect, or misplaced part	Rejected		√
Newton's rings	Area $<1/6$ screen area quantity $\leq 1$	Accepted		√
Mura	1.In black/gray display ND 5% invisible ->OK; visible->NG 2.Naked eyes inspection RGB display invisible Black display, area $<1/4$ screen area	Refer to limited sample 		√
Light leak	1.LCD edge (near backlight) shadow by LCD lamps irregular illuminate 2.Judge in black/white/gray display (slight leaky is yellowish,greenish, blueish ->NG) ; 	Refer to limited sample		√
Polarizer	1.Polarizer slant.Cover VA and not over LCD edge 2.No unmovable stain or finger print in polarizer VA	Accepted		√

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	3.Bubble/warped but not enter VA			
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#### 6.4.General Appearance and Dimension(Major)

Common inspection equipment :micro calliper 、 vernier caliper 、 pencil hardness tester 、 spectrophotometer 、 drop ball test and etc.

Items	Spec
Dimension	According to drawing
Curl	≤0.3% -> OK, "S" curl ->NG
Surface hardness	According to drawing
VA TT (550nm)	According to drawing
IR TT-- (550nm & 850nm)	According to drawing
Intensity (drop ball test)	According to drawing

Remark: the criterion is common for all product and if some components are not included, just ignore it.

#### 7. Others

Items not specified in this document or released on compromise should be inspected with reference to mutual agreement and limit samples.